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| |  | | --- | |  | | Expected Salary: | | **MYR 5300** | | **Brian Wong** Equipment Engineer at Infineon Technologies (Kulim) Sdn Bhd | |
| (+60) 0125641518 | wcw.brian@gmail.com | 32 years old | Alor Setar, Kedah | |
| Experience | 7 years |
| Previous | Specialist Engineer Western Digital Coporation |
| Education | University Malaysia Perlis Bach Degree, Microelectronics Engineering (2007) |
| Nationality | Malaysian |
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| **Experience** | | |
| Jun 2011 - Present (2 years 10 months ) | **Engineer**  Infineon Technologies (Kulim) Sdn Bhd | |
|  | **Job Scope** |  |
|  | Involve in PVD Equipment , Front Side and Back Side Metallization  Maintenance Tool lead for Endura and Clusterline Tool.  PVD Sputter Tool Start up – Start up Tool Clusterline and Endura.  Plan Tool Budgetary – Fix the budget on spending per month for related tool.  **Achievements**  Reduce UD( Unplanned Downtime) from 5% to current 4% ( modifying kit design)  Increase Tool uptime to a current High of 87 % ( by reducing wafer break/slide as well as reduce SD(Schedule Downtime) from 7% to 5% )  Achieve and maintain a tool budgetary budget and keeping to it at 22,000 Euro per month.  **Responsibilities**  Now currently working in Infineon Technologies as an Equipment Engineer as well as Tool Owner For PVD Department  Involved in Endura Platform 8 inch wafer production.  Plan on a Monthly Basis on budgetary budget to buy and maintain tool spare and upkeep  Previously is a tool owner for 11 PVD Endura Production tools in Infineon Technologies Kulim.  Currently involve in back side metallization PVD Clusterline tool since Sep 2013  Involve in new tool startup Clusterline PVDCL 2006 8 inch wafer production.  Work closely with the PVD Sputter team on Tool Uptime as well as Tool Improvements on the tool  **Project**  - Involve in Target life extension project for PVD Endura tool  - Fast Venting Time with new Diffuser implementation as well fast wafer mapping installation ( Improve tool production time by 1% by increasing venting time  - Load lock Laser Implementation and cool down sensor ( wafer scratch issue)  - Dual HDD Design for better management of Recipes for the tool.  - Implement STB Box (SECs GEM). Cost reduction Project.(Parts Cost Lesser) | |
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| Sep 2007 - Jun 2011 (3 years 9 months ) | **Engineer** Western Digital Coporation | |
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|  | Sputtering Department. Involved in Intevac MDP 250 B Sputter Tool and Anelva 3050i  **Achievements**  Meet Quarterly and Yearly SU ( Sputter Utilization ) for the Intevac MDB tools Line 1 to Line 3 ~ SU 80 %  Achieve Sputter Yield target set ~ 90%  Reduce disk drop by 2% by implementing 1 service and 1 change ( ball screw)  **Responsibilities:**  Take the lead role in leading technicians to troubleshoot machine problems and to ensure the smooth running of the machine operations. Lead 6 Shift technicians   Responsible for the system upbringing and maintenance issues. System owner for Intevac lines.  Responsible as an ISO Coordinator for the team.  Work closely with the team on SU (Sputter Utilization) and also with other teams (Process/Yield) for sputter improvement.   **EXPERIENCES GAINED:**  Experience in Vacuum Technology . Experience in Intevac MDP 250B. Learned about High Vacuum Pumps ( Turbopumps, Cyropumps, Waterpumps) , High Vacuum Valves and how they work.   Experience in sputter machinery tool ( Intevac MDP250B and Anelva 3050i), skilled in use of internet, software applications including PowerPoint, Word. Excellent oral and written communication skills.   Did a project on Turbopump Project Improvement  Involved Projects. (With Brief description)  Using a V302/V551 Turbopump to Replace a V301 Turbopump .  Calculate and demonstrate the usage of the V551 and V302 Turbopump to replace existing V301 Turbopump due to lifespan of V301 turbopump  OMS Card Replacement Project. Replacement of OMS Card to old OMS card due to OMS SRX card no replacement  Stinger Gauge Project. Replacement of Thermo couple Gauge (TC Gauge) to Stinger Gauge due to Stinger Gauge Having a faster response time.  REASON FOR LEAVING:  Seek a better career prospect and to better oneself in terms of technical capabilities. | |
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| **Education** | | |
| 2007 | **University Malaysia Perlis** Bachelor's Degree in Microelectronics Engineering | Malaysia | |
|  | Major | Microelectronics |
|  | CGPA | 2.96/4 |
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| 2003 | **Politeknik Sultan Abdul Halim Muadzam Shah** Diploma in Engineering (Mechatronic/Electromechanical) | Malaysia | |
|  | Major | Mechatronics |
|  | CGPA | 3.0/4 |
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| **Skills** | | |
| Basic | Visual Basic, PLC Siemes S5 , Microsoft Excel | |
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| **Languages** | | |
| *Proficiency level: 0 - Poor, 10 - Excellent* | | |
| Language | Spoken Written Relevant Certificates | |
| English | 9 9 - | |
| Bahasa Malaysia | 8 8 - | |
| Chinese | 5 0 - | |
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| Jobstreet English Language Assessment (JELA) | | |
| Date Taken | 12 Apr 2010 | |
| Score | 37/40 | |
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| **Additional Info** | | |
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| Preferred Work Location | Penang, Kedah, Kuala Lumpur | |
| Other Information |  |  |
| **CAREER OBJECTIVE:**  Full-time position in a multinational corporation which offers a professional working environment and enabling me to grow while meeting the corporation's goals.  **STRENGTHS:** - Strong academic background in microelectronics engineering with a CGPA of 2.96/4.00. - Excellent communication skills with fluency in the English Language.   * Able to work in a team and to communicate to both top and lower management.  **PROFESSIONAL EXPERIENCE**: Test Engineering Intern, PLEXUS SDN. BHD  - Involved in the test development of 5DX system. - Involved in improving the test yield of the 5DX system.  **ADDITIONAL SKILLS:** - Proficient in Microsoft Office applications. - Excellent oral and written English. - Possess a car and motorcycle driving licence. - Possess own transport. | | |
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| **About Me** | | |
| Gender | Male | |
| Telephone Number | (+6012 – 5641518 / 0175661058 ) | |
| Address | 140 Taman Bukit Ria ,Jalan Sentosa 14000 Bukit Mertajam Pulau Pinang | |
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